

REMARKS

Claims 2-7 and 9-22 are currently pending based on the amendment herein. Claims 1 and 8 have been cancelled. Claims 2-6, 9, and 11 have been amended. Claims 14-22 are new.

CONCLUSION

Based on the preceding arguments, Applicants respectfully believe that all claims 2-7 and 9-22 meet the acceptance criteria for allowance and therefore request favorable action. If the Examiner believes that anything further would be helpful to place the application in better condition for allowance, Applicants invite the Examiner to contact Applicants' representative at the telephone number listed below.

Date: 07/25/2002

Schmeiser, Olsen & Watts
3 Lear Jet Lane
Ithaca, New York 14850
(518) 220-1850

Jack P. Friedman
Jack P. Friedman
Registration No. 44,688

09/526,957

8

Appendix A. Identification of Amended Material

Claims 2-6, 9, and 11 are amended as follows:

2. (AMENDED) [The electronic structure of claim 1,] An electronic structure, comprising:

a substrate;

a first circuit line including a first conductive pad and having a first thickness extending in a direction perpendicular to a surface of the substrate at which the first circuit line is coupled to the substrate, and wherein the first circuit line is totally external to the substrate aside from being in contact with the substrate; and

a second circuit line including a second conductive pad and having a second thickness extending in a direction perpendicular to a surface of the substrate at which the second circuit line is coupled to the substrate, wherein the second circuit line is electrically coupled to the first circuit line, wherein the second thickness is unequal to the first thickness, wherein the second circuit line is totally external to the substrate aside from being in contact with the substrate, and wherein the first circuit line is in direct mechanical contact with the second circuit line.

3. (AMENDED) [The electronic structure of claim 1, wherein said electrical coupling between the first circuit line and the second circuit line includes a third circuit line] An electronic structure, comprising:

a substrate;

a first circuit line including a first conductive pad and having a first thickness extending in a direction perpendicular to a surface of the substrate at which the first circuit line is coupled to

the substrate, and wherein the first circuit line is totally external to the substrate aside from being in contact with the substrate;

a second circuit line including a second conductive pad and having a second thickness extending in a direction perpendicular to a surface of the substrate at which the second circuit line is coupled to the substrate, wherein the second circuit line is electrically coupled to the first circuit line, wherein the second thickness is unequal to the first thickness, and wherein the second circuit line is totally external to the substrate aside from being in contact with the substrate; and

a third circuit line coupled to the substrate, wherein the third circuit line has a third thickness that is unequal to both the first thickness and the second thickness, wherein a portion of the third circuit line is electrically coupled to a portion of the first circuit line, [and] wherein a portion of the third circuit line is electrically coupled to a portion of the second circuit line, wherein the third thickness extends in a direction perpendicular to a surface of the substrate at which the third circuit line is coupled to the substrate, and wherein the third circuit line is totally external to the substrate aside from being in contact with the substrate.

4. (AMENDED) The electronic structure of claim [1] 2, wherein an end of the first circuit line includes the first conductive pad, and wherein an end of the second circuit line includes the second conductive pad.

5. (AMENDED) The electronic structure of claim [1] 2, further comprising a protective coating that covers a portion of a circuit line, wherein the circuit line includes the first circuit line and the second circuit line.

6. (AMENDED) The electronic structure of claim [1] 2, wherein the [first circuit line is mechanically coupled to a first] surface of the substrate to which the first circuit line is coupled is a top surface of the substrate, and wherein the [second circuit line is mechanically coupled to a second] surface of the substrate to which the second circuit line is coupled is a bottom surface of the substrate.

9. (AMENDED) The electronic structure of claim [1] 2, further comprising:

- a first solder ball coupled to the first conductive pad;
- an electronic assembly coupled to the first solder ball;
- a second solder ball coupled to the second conductive pad; and
- an electronic carrier coupled to the second solder ball.

11. (AMENDED) The electronic structure of claim [1] 2, wherein the first conductive pad includes a metallic layer, and further comprising:

- a first metallic coating over the metallic layer; and
- a second metallic coating over the first metallic coating, wherein the first metallic coating inhibits diffusion of a metal from the second metallic coating into the metallic layer.